



Welcome to [E-XFL.COM](https://www.e-xfl.com)

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	400
Number of Logic Elements/Cells	950
Total RAM Bits	12800
Number of I/O	160
Number of Gates	10000
Voltage - Supply	3V ~ 3.6V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	256-BBGA
Supplier Device Package	256-PBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc4010xl-2bg256i

Table 1: XC4000E and XC4000X Series Field Programmable Gate Arrays

Device	Logic Cells	Max Logic Gates (No RAM)	Max. RAM Bits (No Logic)	Typical Gate Range (Logic and RAM)*	CLB Matrix	Total CLBs	Number of Flip-Flops	Max. User I/O
XC4002XL	152	1,600	2,048	1,000 - 3,000	8 x 8	64	256	64
XC4003E	238	3,000	3,200	2,000 - 5,000	10 x 10	100	360	80
XC4005E/XL	466	5,000	6,272	3,000 - 9,000	14 x 14	196	616	112
XC4006E	608	6,000	8,192	4,000 - 12,000	16 x 16	256	768	128
XC4008E	770	8,000	10,368	6,000 - 15,000	18 x 18	324	936	144
XC4010E/XL	950	10,000	12,800	7,000 - 20,000	20 x 20	400	1,120	160
XC4013E/XL	1368	13,000	18,432	10,000 - 30,000	24 x 24	576	1,536	192
XC4020E/XL	1862	20,000	25,088	13,000 - 40,000	28 x 28	784	2,016	224
XC4025E	2432	25,000	32,768	15,000 - 45,000	32 x 32	1,024	2,560	256
XC4028EX/XL	2432	28,000	32,768	18,000 - 50,000	32 x 32	1,024	2,560	256
XC4036EX/XL	3078	36,000	41,472	22,000 - 65,000	36 x 36	1,296	3,168	288
XC4044XL	3800	44,000	51,200	27,000 - 80,000	40 x 40	1,600	3,840	320
XC4052XL	4598	52,000	61,952	33,000 - 100,000	44 x 44	1,936	4,576	352
XC4062XL	5472	62,000	73,728	40,000 - 130,000	48 x 48	2,304	5,376	384
XC4085XL	7448	85,000	100,352	55,000 - 180,000	56 x 56	3,136	7,168	448

* Max values of Typical Gate Range include 20-30% of CLBs used as RAM.

Note: All functionality in low-voltage families is the same as in the corresponding 5-Volt family, except where numerical references are made to timing or power.

Description

XC4000 Series devices are implemented with a regular, flexible, programmable architecture of Configurable Logic Blocks (CLBs), interconnected by a powerful hierarchy of versatile routing resources, and surrounded by a perimeter of programmable Input/Output Blocks (IOBs). They have generous routing resources to accommodate the most complex interconnect patterns.

The devices are customized by loading configuration data into internal memory cells. The FPGA can either actively read its configuration data from an external serial or byte-parallel PROM (master modes), or the configuration data can be written into the FPGA from an external device (slave and peripheral modes).

XC4000 Series FPGAs are supported by powerful and sophisticated software, covering every aspect of design from schematic or behavioral entry, floor planning, simulation, automatic block placement and routing of interconnects, to the creation, downloading, and readback of the configuration bit stream.

Because Xilinx FPGAs can be reprogrammed an unlimited number of times, they can be used in innovative designs

where hardware is changed dynamically, or where hardware must be adapted to different user applications. FPGAs are ideal for shortening design and development cycles, and also offer a cost-effective solution for production rates well beyond 5,000 systems per month.

Taking Advantage of Re-configuration

FPGA devices can be re-configured to change logic function while resident in the system. This capability gives the system designer a new degree of freedom not available with any other type of logic.

Hardware can be changed as easily as software. Design updates or modifications are easy, and can be made to products already in the field. An FPGA can even be re-configured dynamically to perform different functions at different times.

Re-configurable logic can be used to implement system self-diagnostics, create systems capable of being re-configured for different environments or operations, or implement multi-purpose hardware for a given application. As an added benefit, using re-configurable FPGA devices simplifies hardware design and debugging and shortens product time-to-market.

Input Thresholds

The input thresholds of 5V devices can be globally configured for either TTL (1.2 V threshold) or CMOS (2.5 V threshold), just like XC2000 and XC3000 inputs. The two global adjustments of input threshold and output level are independent of each other. The XC4000XL family has an input threshold of 1.6V, compatible with both 3.3V CMOS and TTL levels.

Global Signal Access to Logic

There is additional access from global clocks to the F and G function generator inputs.

Configuration Pin Pull-Up Resistors

During configuration, these pins have weak pull-up resistors. For the most popular configuration mode, Slave Serial, the mode pins can thus be left unconnected. The three mode inputs can be individually configured with or without weak pull-up or pull-down resistors. A pull-down resistor value of 4.7 k Ω is recommended.

The three mode inputs can be individually configured with or without weak pull-up or pull-down resistors after configuration.

The PROGRAM input pin has a permanent weak pull-up.

Soft Start-up

Like the XC3000A, XC4000 Series devices have "Soft Start-up." When the configuration process is finished and the device starts up, the first activation of the outputs is automatically slew-rate limited. This feature avoids potential ground bounce when all outputs are turned on simultaneously. Immediately after start-up, the slew rate of the individual outputs is, as in the XC4000 family, determined by the individual configuration option.

XC4000 and XC4000A Compatibility

Existing XC4000 bitstreams can be used to configure an XC4000E device. XC4000A bitstreams must be recompiled for use with the XC4000E due to improved routing resources, although the devices are pin-for-pin compatible.

Additional Improvements in XC4000X Only

Increased Routing

New interconnect in the XC4000X includes twenty-two additional vertical lines in each column of CLBs and twelve new horizontal lines in each row of CLBs. The twelve "Quad Lines" in each CLB row and column include optional repowering buffers for maximum speed. Additional high-performance routing near the IOBs enhances pin flexibility.

Faster Input and Output

A fast, dedicated early clock sourced by global clock buffers is available for the IOBs. To ensure synchronization with the regular global clocks, a Fast Capture latch driven by the early clock is available. The input data can be initially loaded into the Fast Capture latch with the early clock, then transferred to the input flip-flop or latch with the low-skew global clock. A programmable delay on the input can be used to avoid hold-time requirements. See "IOB Input Signals" on page 20 for more information.

Latch Capability in CLBs

Storage elements in the XC4000X CLB can be configured as either flip-flops or latches. This capability makes the FPGA highly synthesis-compatible.

IOB Output MUX From Output Clock

A multiplexer in the IOB allows the output clock to select either the output data or the IOB clock enable as the output to the pad. Thus, two different data signals can share a single output pad, effectively doubling the number of device outputs without requiring a larger, more expensive package. This multiplexer can also be configured as an AND-gate to implement a very fast pin-to-pin path. See "IOB Output Signals" on page 23 for more information.

Additional Address Bits

Larger devices require more bits of configuration data. A daisy chain of several large XC4000X devices may require a PROM that cannot be addressed by the eighteen address bits supported in the XC4000E. The XC4000X Series therefore extends the addressing in Master Parallel configuration mode to 22 bits.

tions of the CLB, with the exception of the redefinition of the control signals. In 16x2 and 16x1 modes, the H' function generator can be used to implement Boolean functions of F', G', and D1, and the D flip-flops can latch the F', G', H', or D0 signals.

Single-Port Edge-Triggered Mode

Edge-triggered (synchronous) RAM simplifies timing requirements. XC4000 Series edge-triggered RAM timing operates like writing to a data register. Data and address are presented. The register is enabled for writing by a logic High on the write enable input, WE. Then a rising or falling clock edge loads the data into the register, as shown in Figure 3.

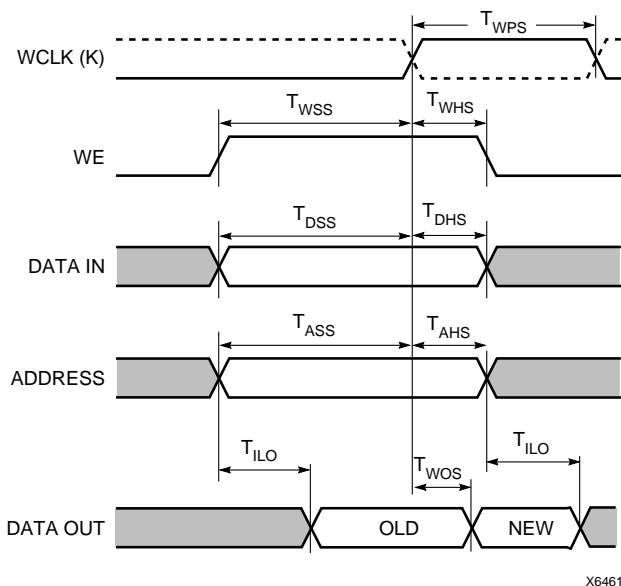


Figure 3: Edge-Triggered RAM Write Timing

Complex timing relationships between address, data, and write enable signals are not required, and the external write enable pulse becomes a simple clock enable. The active edge of WCLK latches the address, input data, and WE sig-

nals. An internal write pulse is generated that performs the write. See Figure 4 and Figure 5 for block diagrams of a CLB configured as 16x2 and 32x1 edge-triggered, single-port RAM.

The relationships between CLB pins and RAM inputs and outputs for single-port, edge-triggered mode are shown in Table 5.

The Write Clock input (WCLK) can be configured as active on either the rising edge (default) or the falling edge. It uses the same CLB pin (K) used to clock the CLB flip-flops, but it can be independently inverted. Consequently, the RAM output can optionally be registered within the same CLB either by the same clock edge as the RAM, or by the opposite edge of this clock. The sense of WCLK applies to both function generators in the CLB when both are configured as RAM.

The WE pin is active-High and is not invertible within the CLB.

Note: The pulse following the active edge of WCLK (T_{WPS} in Figure 3) must be less than one millisecond wide. For most applications, this requirement is not overly restrictive; however, it must not be forgotten. Stopping WCLK at this point in the write cycle could result in excessive current and even damage to the larger devices if many CLBs are configured as edge-triggered RAM.

Table 5: Single-Port Edge-Triggered RAM Signals

RAM Signal	CLB Pin	Function
D	D0 or D1 (16x2, 16x1), D0 (32x1)	Data In
A[3:0]	F1-F4 or G1-G4	Address
A[4]	D1 (32x1)	Address
WE	WE	Write Enable
WCLK	K	Clock
SPO (Data Out)	F' or G'	Single Port Out (Data Out)

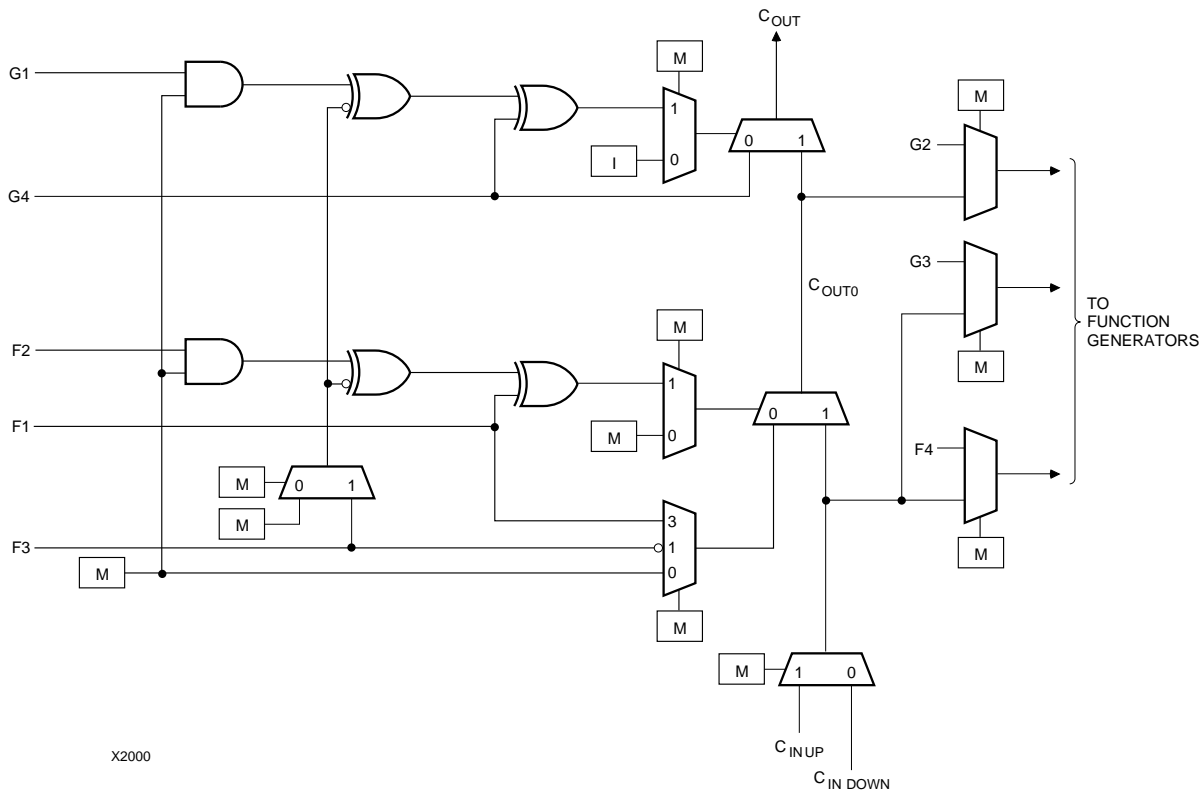


Figure 14: Detail of XC4000E Dedicated Carry Logic

Input/Output Blocks (IOBs)

User-configurable input/output blocks (IOBs) provide the interface between external package pins and the internal logic. Each IOB controls one package pin and can be configured for input, output, or bidirectional signals.

Figure 15 shows a simplified block diagram of the XC4000E IOB. A more complete diagram which includes the boundary scan logic of the XC4000E IOB can be found in Figure 40 on page 43, in the “Boundary Scan” section.

The XC4000X IOB contains some special features not included in the XC4000E IOB. These features are highlighted in a simplified block diagram found in [Figure 16](#), and discussed throughout this section. When XC4000X special features are discussed, they are clearly identified in the text. Any feature not so identified is present in both XC4000E and XC4000X devices.

I/O Input Signals

Two paths, labeled I1 and I2 in [Figure 15](#) and [Figure 16](#), bring input signals into the array. Inputs also connect to an input register that can be programmed as either an edge-triggered flip-flop or a level-sensitive latch.

The choice is made by placing the appropriate library symbol. For example, IFD is the basic input flip-flop (rising edge triggered), and ILD is the basic input latch (transparent-High). Variations with inverted clocks are available, and some combinations of latches and flip-flops can be implemented in a single IOB, as described in the *XACT Libraries Guide*.

The XC4000E inputs can be globally configured for either TTL (1.2V) or 5.0 volt CMOS thresholds, using an option in the bitstream generation software. There is a slight input hysteresis of about 300mV. The XC4000E output levels are also configurable; the two global adjustments of input threshold and output level are independent.

Inputs on the XC4000XL are TTL compatible and 3.3V CMOS compatible. Outputs on the XC4000XL are pulled to the 3.3V positive supply.

The inputs of XC4000 Series 5-Volt devices can be driven by the outputs of any 3.3-Volt device, if the 5-Volt inputs are in TTL mode.

Supported sources for XC4000 Series device inputs are shown in [Table 8](#).

Table 8: Supported Sources for XC4000 Series Device Inputs

Source	XC4000E/EX Series Inputs		XC4000XL Series Inputs
	5 V, TTL	5 V, CMOS	3.3 V CMOS
Any device, V _{CC} = 3.3 V, CMOS outputs	✓	Unreliable Data	✓
XC4000 Series, V _{CC} = 5 V, TTL outputs	✓		✓
Any device, V _{CC} = 5 V, TTL outputs (V _{oh} ≤ 3.7 V)	✓		✓
Any device, V _{CC} = 5 V, CMOS outputs	✓	✓	✓

XC4000XL 5-Volt Tolerant I/Os

The I/Os on the XC4000XL are fully 5-volt tolerant even though the V_{CC} is 3.3 volts. This allows 5 V signals to directly connect to the XC4000XL inputs without damage, as shown in [Table 8](#). In addition, the 3.3 volt V_{CC} can be applied before or after 5 volt signals are applied to the I/Os. This makes the XC4000XL immune to power supply sequencing problems.


Registered Inputs

The I1 and I2 signals that exit the block can each carry either the direct or registered input signal.

The input and output storage elements in each IOB have a common clock enable input, which, through configuration, can be activated individually for the input or output flip-flop, or both. This clock enable operates exactly like the EC pin on the XC4000 Series CLB. It cannot be inverted within the IOB.

The storage element behavior is shown in [Table 9](#).

Table 9: Input Register Functionality (active rising edge is shown)

Mode	Clock	Clock Enable	D	Q
Power-Up or GSR	X	X	X	SR
Flip-Flop		1*	D	D
	0	X	X	Q
Latch	1	1*	X	Q
	0	1*	D	D
Both	X	0	X	Q

Legend:

X 

SR

0*

1*

Don't care
Rising edge

Set or Reset value. Reset is default.

Input is Low or unconnected (default value)

Input is High or unconnected (default value)

Optional Delay Guarantees Zero Hold Time

The data input to the register can optionally be delayed by several nanoseconds. With the delay enabled, the setup time of the input flip-flop is increased so that normal clock routing does not result in a positive hold-time requirement. A positive hold time requirement can lead to unreliable, temperature- or processing-dependent operation.

The input flip-flop setup time is defined between the data measured at the device I/O pin and the clock input at the IOB (not at the clock pin). Any routing delay from the device clock pin to the clock input of the IOB must, therefore, be subtracted from this setup time to arrive at the real setup time requirement relative to the device pins. A short specified setup time might, therefore, result in a negative setup time at the device pins, i.e., a positive hold-time requirement.

When a delay is inserted on the data line, more clock delay can be tolerated without causing a positive hold-time requirement. Sufficient delay eliminates the possibility of a data hold-time requirement at the external pin. The maximum delay is therefore inserted as the default.

The XC4000E IOB has a one-tap delay element: either the delay is inserted (default), or it is not. The delay guarantees a zero hold time with respect to clocks routed through any of the XC4000E global clock buffers. (See [“Global Nets and Buffers \(XC4000E only\)” on page 35](#) for a description of the global clock buffers in the XC4000E.) For a shorter input register setup time, with non-zero hold, attach a NODELAY attribute or property to the flip-flop.

The XC4000X IOB has a two-tap delay element, with choices of a full delay, a partial delay, or no delay. The attributes or properties used to select the desired delay are shown in [Table 10](#). The choices are no added attribute, MEDDELAY, and NODELAY. The default setting, with no added attribute, ensures no hold time with respect to any of the XC4000X clock buffers, including the Global Low-Skew buffers. MEDDELAY ensures no hold time with respect to the Global Early buffers. Inputs with NODELAY may have a positive hold time with respect to all clock buffers. For a description of each of these buffers, see [“Global Nets and Buffers \(XC4000X only\)” on page 37](#).

Table 10: XC4000X IOB Input Delay Element

Value	When to Use
full delay (default, no attribute added)	Zero Hold with respect to Global Low-Skew Buffer, Global Early Buffer
MEDDELAY	Zero Hold with respect to Global Early Buffer
NODELAY	Short Setup, positive Hold time

circuit prevents undefined floating levels. However, it is overridden by any driver, even a pull-up resistor.

Each XC4000E longline has a programmable splitter switch at its center, as does each XC4000X longline driven by TBUFs. This switch can separate the line into two independent routing channels, each running half the width or height of the array.

Each XC4000X longline not driven by TBUFs has a buffered programmable splitter switch at the 1/4, 1/2, and 3/4 points of the array. Due to the buffering, XC4000X longline performance does not deteriorate with the larger array sizes. If the longline is split, the resulting partial longlines are independent.

Routing connectivity of the longlines is shown in [Figure 27 on page 30](#).

Direct Interconnect (XC4000X only)

The XC4000X offers two direct, efficient and fast connections between adjacent CLBs. These nets facilitate a data flow from the left to the right side of the device, or from the top to the bottom, as shown in [Figure 30](#). Signals routed on the direct interconnect exhibit minimum interconnect propagation delay and use no general routing resources.

The direct interconnect is also present between CLBs and adjacent IOBs. Each IOB on the left and top device edges has a direct path to the nearest CLB. Each CLB on the right and bottom edges of the array has a direct path to the nearest two IOBs, since there are two IOBs for each row or column of CLBs.

The place and route software uses direct interconnect whenever possible, to maximize routing resources and minimize interconnect delays.



Figure 30: XC4000X Direct Interconnect

I/O Routing

XC4000 Series devices have additional routing around the IOB ring. This routing is called a VersaRing. The VersaRing facilitates pin-swapping and redesign without affecting board layout. Included are eight double-length lines spanning two CLBs (four IOBs), and four longlines. Global lines and Wide Edge Decoder lines are provided. XC4000X devices also include eight octal lines.

A high-level diagram of the VersaRing is shown in [Figure 31](#). The shaded arrows represent routing present only in XC4000X devices.

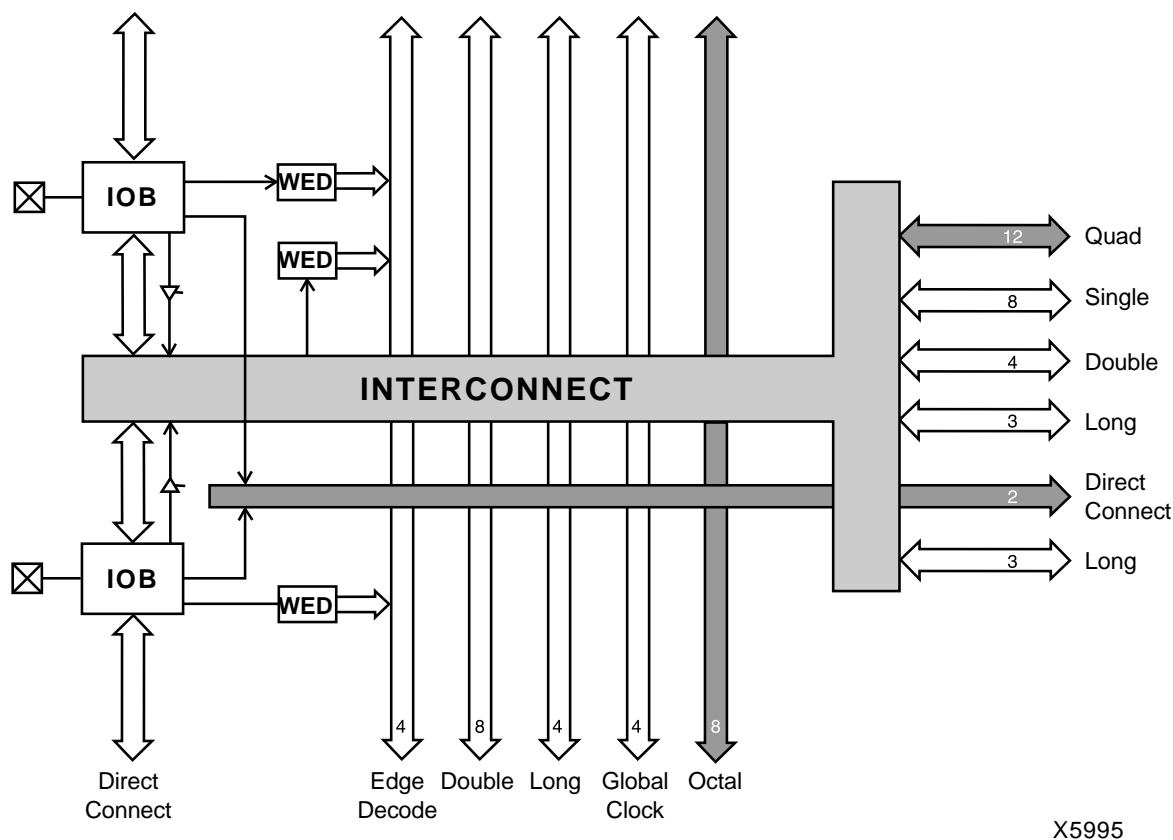
[Figure 33 on page 34](#) is a detailed diagram of the XC4000E and XC4000X VersaRing. The area shown includes two IOBs. There are two IOBs per CLB row or column, therefore this diagram corresponds to the CLB routing diagram shown in [Figure 27 on page 30](#). The shaded areas represent routing and routing connections present only in XC4000X devices.

Octal I/O Routing (XC4000X only)

Between the XC4000X CLB array and the pad ring, eight interconnect tracks provide for versatility in pin assignment and fixed pinout flexibility. (See [Figure 32 on page 33](#).)

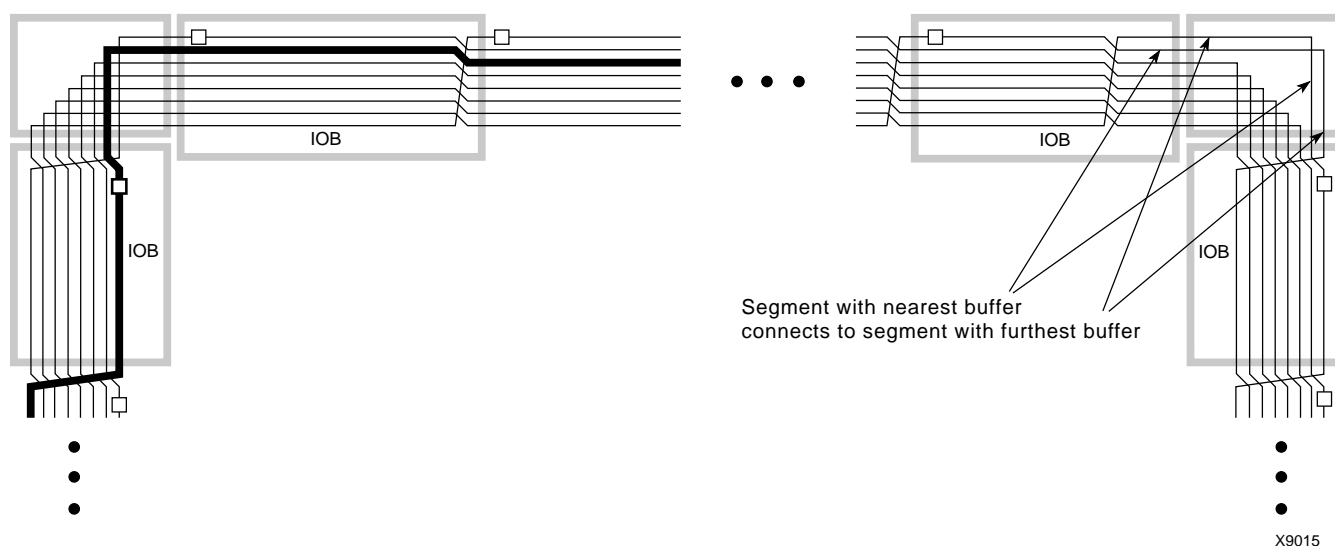
These routing tracks are called octals, because they can be broken every eight CLBs (sixteen IOBs) by a programmable buffer that also functions as a splitter switch. The buffers are staggered, so each line goes through a buffer at every eighth CLB location around the device edge.

The octal lines bend around the corners of the device. The lines cross at the corners in such a way that the segment most recently buffered before the turn has the farthest distance to travel before the next buffer, as shown in [Figure 32](#).



X5995

Figure 31: High-Level Routing Diagram of XC4000 Series VersaRing (Left Edge)
WED = Wide Edge Decoder, IOB = I/O Block (shaded arrows indicate XC4000X only)



X9015

Figure 32: XC4000X Octal I/O Routing

The top and bottom Global Early buffers are about 1 ns slower clock to out than the left and right Global Early buffers.

The Global Early buffers can be driven by either semi-dedicated pads or internal logic. They share pads with the Global Low-Skew buffers, so a single net can drive both global buffers, as described above.

To use a Global Early buffer, place a BUFGE element in a schematic or in HDL code. If desired, attach a LOC attribute or property to direct placement to the designated location. For example, attach a LOC=T attribute or property to direct that a BUFGE be placed in one of the two Global Early buffers on the top edge of the device, or a LOC=TR to indicate the Global Early buffer on the top edge of the device, on the right.

Power Distribution

Power for the FPGA is distributed through a grid to achieve high noise immunity and isolation between logic and I/O. Inside the FPGA, a dedicated Vcc and Ground ring surrounding the logic array provides power to the I/O drivers, as shown in [Figure 39](#). An independent matrix of Vcc and Ground lines supplies the interior logic of the device.

This power distribution grid provides a stable supply and ground for all internal logic, providing the external package power pins are all connected and appropriately de-coupled. Typically, a 0.1 μ F capacitor connected between each Vcc pin and the board's Ground plane will provide adequate de-coupling.

Output buffers capable of driving/sinking the specified 12 mA loads under specified worst-case conditions may be capable of driving/sinking up to 10 times as much current under best case conditions.

Noise can be reduced by minimizing external load capacitance and reducing simultaneous output transitions in the same direction. It may also be beneficial to locate heavily loaded output buffers near the Ground pads. The I/O Block output buffers have a slew-rate limited mode (default) which should be used where output rise and fall times are not speed-critical.



Figure 39: XC4000 Series Power Distribution

Pin Descriptions

There are three types of pins in the XC4000 Series devices:

- Permanently dedicated pins
- User I/O pins that can have special functions
- Unrestricted user-programmable I/O pins.

Before and during configuration, all outputs not used for the configuration process are 3-stated with a 50 k Ω - 100 k Ω pull-up resistor.

After configuration, if an IOB is unused it is configured as an input with a 50 k Ω - 100 k Ω pull-up resistor.

XC4000 Series devices have no dedicated Reset input. Any user I/O can be configured to drive the Global Set/Reset net, GSR. See [“Global Set/Reset” on page 11](#) for more information on GSR.

XC4000 Series devices have no Powerdown control input, as the XC3000 and XC2000 families do. The XC3000/XC2000 Powerdown control also 3-stated all of the device

I/O pins. For XC4000 Series devices, use the global 3-state net, GTS, instead. This net 3-states all outputs, but does not place the device in low-power mode. See [“IOB Output Signals” on page 23](#) for more information on GTS.

Device pins for XC4000 Series devices are described in [Table 16](#). Pin functions during configuration for each of the seven configuration modes are summarized in [Table 22 on page 58](#), in the “Configuration Timing” section.

Table 16: Pin Descriptions (Continued)

Pin Name	I/O During Config.	I/O After Config.	Pin Description
$\overline{CS0}$, CS1, \overline{WS} , \overline{RS}	I	I/O	These four inputs are used in Asynchronous Peripheral mode. The chip is selected when $\overline{CS0}$ is Low and CS1 is High. While the chip is selected, a Low on Write Strobe (\overline{WS}) loads the data present on the D0 - D7 inputs into the internal data buffer. A Low on Read Strobe (\overline{RS}) changes D7 into a status output — High if Ready, Low if Busy — and drives D0 - D6 High. In Express mode, CS1 is used as a serial-enable signal for daisy-chaining. \overline{WS} and \overline{RS} should be mutually exclusive, but if both are Low simultaneously, the Write Strobe overrides. After configuration, these are user-programmable I/O pins.
A0 - A17	O	I/O	During Master Parallel configuration, these 18 output pins address the configuration EPROM. After configuration, they are user-programmable I/O pins.
A18 - A21 (XC4003XL to XC4085XL)	O	I/O	During Master Parallel configuration with an XC4000X master, these 4 output pins add 4 more bits to address the configuration EPROM. After configuration, they are user-programmable I/O pins. (See Master Parallel Configuration section for additional details.)
D0 - D7	I	I/O	During Master Parallel and Peripheral configuration, these eight input pins receive configuration data. After configuration, they are user-programmable I/O pins.
DIN	I	I/O	During Slave Serial or Master Serial configuration, DIN is the serial configuration data input receiving data on the rising edge of CCLK. During Parallel configuration, DIN is the D0 input. After configuration, DIN is a user-programmable I/O pin.
DOUT	O	I/O	During configuration in any mode but Express mode, DOUT is the serial configuration data output that can drive the DIN of daisy-chained slave FPGAs. DOUT data changes on the falling edge of CCLK, one-and-a-half CCLK periods after it was received at the DIN input. In Express mode for XC4000E and XC4000X only, DOUT is the status output that can drive the CS1 of daisy-chained FPGAs, to enable and disable downstream devices. After configuration, DOUT is a user-programmable I/O pin.
Unrestricted User-Programmable I/O Pins			
I/O	Weak Pull-up	I/O	These pins can be configured to be input and/or output after configuration is completed. Before configuration is completed, these pins have an internal high-value pull-up resistor (25 k Ω - 100 k Ω) that defines the logic level as High.

Boundary Scan

The ‘bed of nails’ has been the traditional method of testing electronic assemblies. This approach has become less appropriate, due to closer pin spacing and more sophisticated assembly methods like surface-mount technology and multi-layer boards. The IEEE Boundary Scan Standard 1149.1 was developed to facilitate board-level testing of electronic assemblies. Design and test engineers can imbed a standard test logic structure in their device to achieve high fault coverage for I/O and internal logic. This structure is easily implemented with a four-pin interface on any boundary scan-compatible IC. IEEE 1149.1-compatible devices may be serial daisy-chained together, connected in parallel, or a combination of the two.

The XC4000 Series implements IEEE 1149.1-compatible BYPASS, PRELOAD/SAMPLE and EXTEST boundary scan instructions. When the boundary scan configuration option is selected, three normal user I/O pins become dedicated inputs for these functions. Another user output pin becomes the dedicated boundary scan output. The details

of how to enable this circuitry are covered later in this section.

By exercising these input signals, the user can serially load commands and data into these devices to control the driving of their outputs and to examine their inputs. This method is an improvement over bed-of-nails testing. It avoids the need to over-drive device outputs, and it reduces the user interface to four pins. An optional fifth pin, a reset for the control logic, is described in the standard but is not implemented in Xilinx devices.

The dedicated on-chip logic implementing the IEEE 1149.1 functions includes a 16-state machine, an instruction register and a number of data registers. The functional details can be found in the IEEE 1149.1 specification and are also discussed in the Xilinx application note XAPP 017: “*Boundary Scan in XC4000 Devices*.”

Figure 40 on page 43 shows a simplified block diagram of the XC4000E Input/Output Block with boundary scan implemented. XC4000X boundary scan logic is identical.

used), and if RAM is present, the RAM content must be unchanged.

Statistically, one error out of 2048 might go undetected.

Configuration Sequence

There are four major steps in the XC4000 Series power-up configuration sequence.

- Configuration Memory Clear
- Initialization
- Configuration
- Start-Up

The full process is illustrated in Figure 46.

Configuration Memory Clear

When power is first applied or is reapplied to an FPGA, an internal circuit forces initialization of the configuration logic. When V_{CC} reaches an operational level, and the circuit passes the write and read test of a sample pair of configuration bits, a time delay is started. This time delay is nominally 16 ms, and up to 10% longer in the low-voltage devices. The delay is four times as long when in Master Modes (M0 Low), to allow ample time for all slaves to reach a stable V_{CC} . When all \overline{INIT} pins are tied together, as recommended, the longest delay takes precedence. Therefore, devices with different time delays can easily be mixed and matched in a daisy chain.

This delay is applied only on power-up. It is not applied when re-configuring an FPGA by pulsing the PROGRAM pin

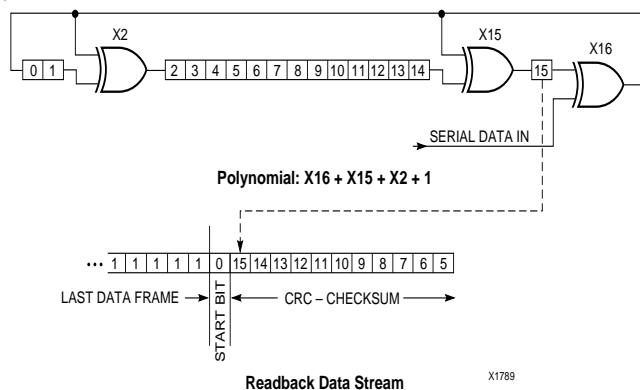


Figure 45: Circuit for Generating CRC-16

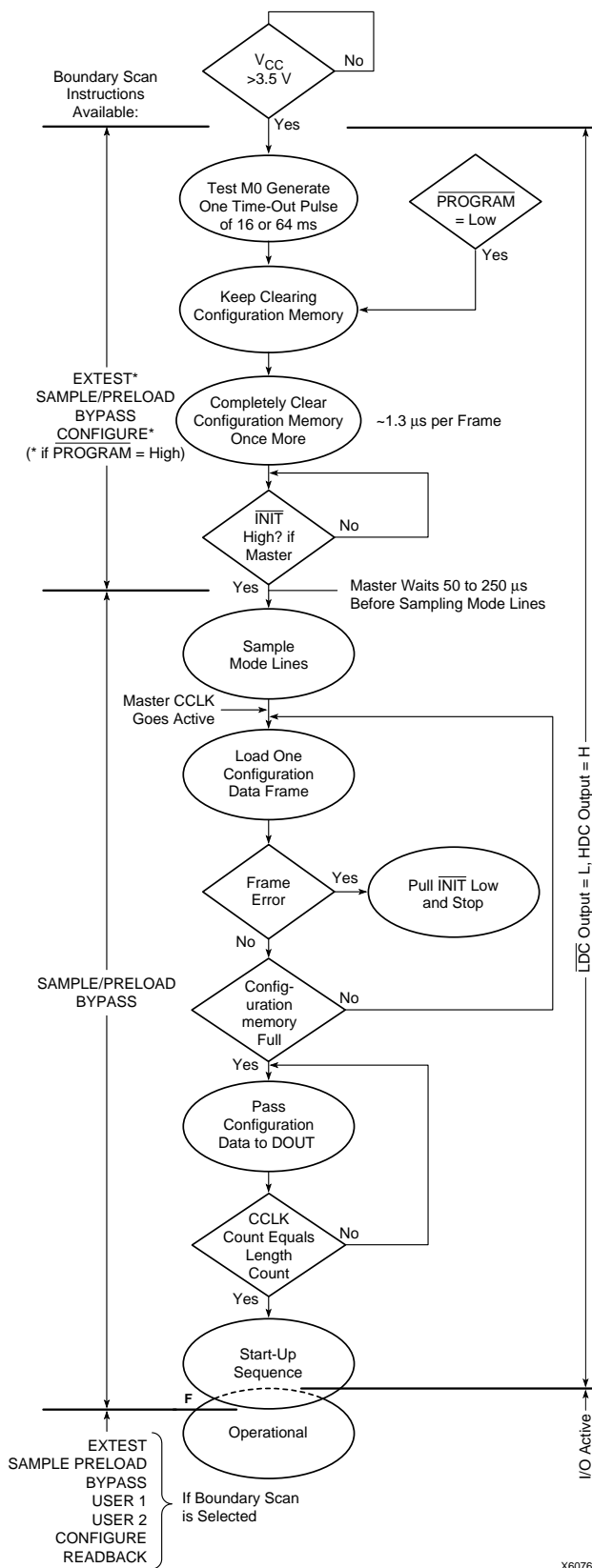


Figure 46: Power-up Configuration Sequence

Low. During this time delay, or as long as the $\overline{\text{PROGRAM}}$ input is asserted, the configuration logic is held in a Configuration Memory Clear state. The configuration-memory frames are consecutively initialized, using the internal oscillator.

At the end of each complete pass through the frame addressing, the power-on time-out delay circuitry and the level of the $\overline{\text{PROGRAM}}$ pin are tested. If neither is asserted, the logic initiates one additional clearing of the configuration frames and then tests the $\overline{\text{INIT}}$ input.

Initialization

During initialization and configuration, user pins HDC , $\overline{\text{LDC}}$, $\overline{\text{INIT}}$ and DONE provide status outputs for the system interface. The outputs $\overline{\text{LDC}}$, $\overline{\text{INIT}}$ and DONE are held Low and HDC is held High starting at the initial application of power.

The open drain $\overline{\text{INIT}}$ pin is released after the final initialization pass through the frame addresses. There is a deliberate delay of 50 to 250 μs (up to 10% longer for low-voltage devices) before a Master-mode device recognizes an inactive $\overline{\text{INIT}}$. Two internal clocks after the $\overline{\text{INIT}}$ pin is recognized as High, the FPGA samples the three mode lines to determine the configuration mode. The appropriate interface lines become active and the configuration preamble and data can be loaded. Configuration

The 0010 preamble code indicates that the following 24 bits represent the length count. The length count is the total number of configuration clocks needed to load the complete configuration data. (Four additional configuration clocks are required to complete the configuration process, as discussed below.) After the preamble and the length count have been passed through to all devices in the daisy chain, DOUT is held High to prevent frame start bits from reaching any daisy-chained devices.

A specific configuration bit, early in the first frame of a master device, controls the configuration-clock rate and can increase it by a factor of eight. Therefore, if a fast configuration clock is selected by the bitstream, the slower clock rate is used until this configuration bit is detected.

Each frame has a start field followed by the frame-configuration data bits and a frame error field. If a frame data error is detected, the FPGA halts loading, and signals the error by pulling the open-drain $\overline{\text{INIT}}$ pin Low. After all configuration frames have been loaded into an FPGA, DOUT again follows the input data so that the remaining data is passed on to the next device.

Delaying Configuration After Power-Up

There are two methods of delaying configuration after power-up: put a logic Low on the $\overline{\text{PROGRAM}}$ input, or pull the bidirectional $\overline{\text{INIT}}$ pin Low, using an open-collector (open-drain) driver. (See [Figure 46 on page 50](#).)

A Low on the $\overline{\text{PROGRAM}}$ input is the more radical approach, and is recommended when the power-supply

rise time is excessive or poorly defined. As long as $\overline{\text{PROGRAM}}$ is Low, the FPGA keeps clearing its configuration memory. When $\overline{\text{PROGRAM}}$ goes High, the configuration memory is cleared one more time, followed by the beginning of configuration, provided the $\overline{\text{INIT}}$ input is not externally held Low. Note that a Low on the $\overline{\text{PROGRAM}}$ input automatically forces a Low on the $\overline{\text{INIT}}$ output. The XC4000 Series $\overline{\text{PROGRAM}}$ pin has a permanent weak pull-up.

Using an open-collector or open-drain driver to hold $\overline{\text{INIT}}$ Low before the beginning of configuration causes the FPGA to wait after completing the configuration memory clear operation. When $\overline{\text{INIT}}$ is no longer held Low externally, the device determines its configuration mode by capturing its mode pins, and is ready to start the configuration process. A master device waits up to an additional 250 μs to make sure that any slaves in the optional daisy chain have seen that $\overline{\text{INIT}}$ is High.

Start-Up

Start-up is the transition from the configuration process to the intended user operation. This transition involves a change from one clock source to another, and a change from interfacing parallel or serial configuration data where most outputs are 3-stated, to normal operation with I/O pins active in the user-system. Start-up must make sure that the user-logic 'wakes up' gracefully, that the outputs become active without causing contention with the configuration signals, and that the internal flip-flops are released from the global Reset or Set at the right time.

[Figure 47](#) describes start-up timing for the three Xilinx families in detail. The configuration modes can use any of the four timing sequences.

To access the internal start-up signals, place the STARTUP library symbol.

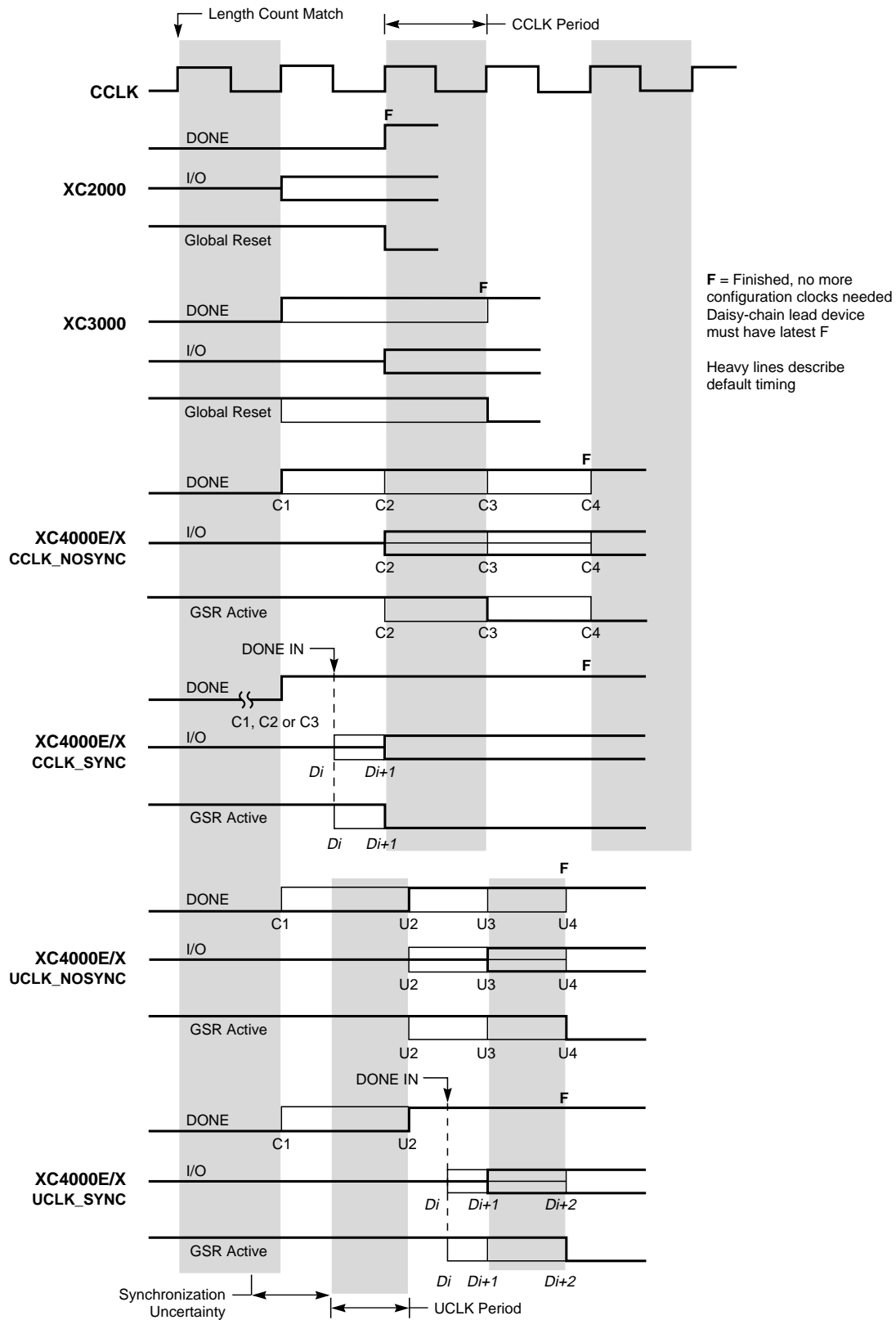
Start-up Timing

Different FPGA families have different start-up sequences.

The XC2000 family goes through a fixed sequence. DONE goes High and the internal global Reset is de-activated one CCLK period after the I/O become active.

The XC3000A family offers some flexibility. DONE can be programmed to go High one CCLK period before or after the I/O become active. Independent of DONE , the internal global Reset is de-activated one CCLK period before or after the I/O become active.

The XC4000 Series offers additional flexibility. The three events — DONE going High, the internal Set/Reset being de-activated, and the user I/O going active — can all occur in any arbitrary sequence. Each of them can occur one CCLK period before or after, or simultaneous with, any of the others. This relative timing is selected by means of software options in the bitstream generation software.



X9024

Figure 47: Start-up Timing

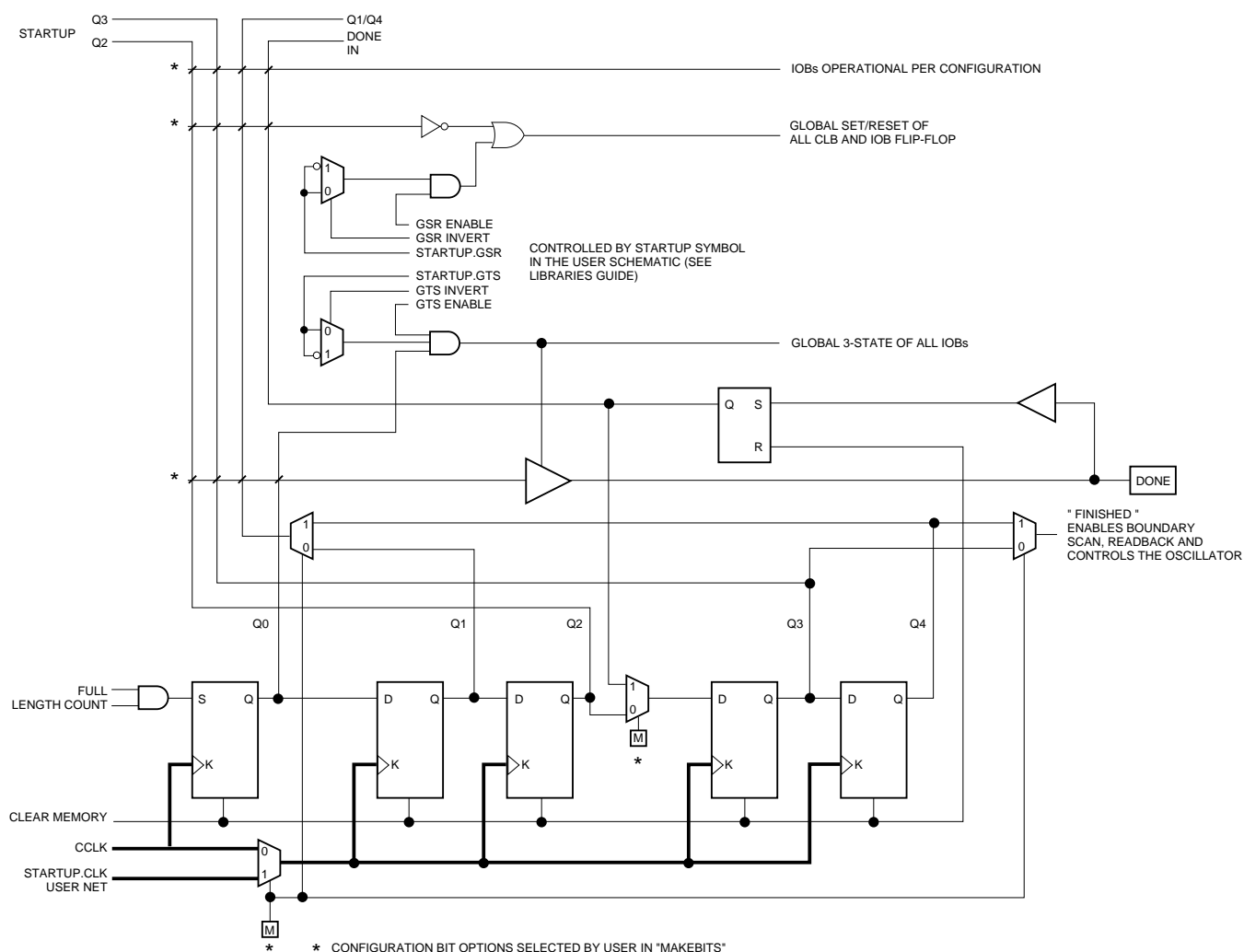


Figure 48: Start-up Logic

Readback

The user can read back the content of configuration memory and the level of certain internal nodes without interfering with the normal operation of the device.

Readback not only reports the downloaded configuration bits, but can also include the present state of the device, represented by the content of all flip-flops and latches in CLBs and IOBs, as well as the content of function generators used as RAMs.

Note that in XC4000 Series devices, configuration data is *not* inverted with respect to configuration as it is in XC2000 and XC3000 families.

XC4000 Series Readback does not use any dedicated pins, but uses four internal nets (RDBK.TRIG, RDBK.DATA, RDBK.RIP and RDBK.CLK) that can be routed to any IOB. To access the internal Readback signals, place the READ-

BACK library symbol and attach the appropriate pad symbols, as shown in Figure 49.

After Readback has been initiated by a High level on RDBK.TRIG after configuration, the RDBK.RIP (Read In Progress) output goes High on the next rising edge of RDBK.CLK. Subsequent rising edges of this clock shift out Readback data on the RDBK.DATA net.

Readback data does not include the preamble, but starts with five dummy bits (all High) followed by the Start bit (Low) of the first frame. The first two data bits of the first frame are always High.

Each frame ends with four error check bits. They are read back as High. The last seven bits of the last frame are also read back as High. An additional Start bit (Low) and an 11-bit Cyclic Redundancy Check (CRC) signature follow, before RDBK.RIP returns Low.

Table 22: Pin Functions During Configuration

CONFIGURATION MODE <M2:M1:M0>						USER OPERATION
SLAVE SERIAL <1:1:1>	MASTER SERIAL <0:0:0>	SYNCH. PERIPHERAL <0:1:1>	ASYNCH. PERIPHERAL <1:0:1>	MASTER PARALLEL DOWN <1:1:0>	MASTER PARALLEL UP <1:0:0>	
M2(HIGH) (I)	M2(LOW) (I)	M2(LOW) (I)	M2(HIGH) (I)	M2(HIGH) (I)	M2(HIGH) (I)	(I)
M1(HIGH) (I)	M1(LOW) (I)	M1(HIGH) (I)	M1(LOW) (I)	M1(HIGH) (I)	M1(LOW) (I)	(O)
M0(HIGH) (I)	M0(LOW) (I)	M0(HIGH) (I)	M0(HIGH) (I)	M0(LOW) (I)	M0(LOW) (I)	(I)
HDC (HIGH)	HDC (HIGH)	HDC (HIGH)	HDC (HIGH)	HDC (HIGH)	HDC (HIGH)	I/O
LDC (LOW)	LDC (LOW)	LDC (LOW)	LDC (LOW)	LDC (LOW)	LDC (LOW)	I/O
INIT	INIT	INIT	INIT	INIT	INIT	I/O
DONE	DONE	DONE	DONE	DONE	DONE	DONE
PROGRAM (I)	PROGRAM (I)	PROGRAM (I)	PROGRAM (I)	PROGRAM (I)	PROGRAM (I)	PROGRAM
CCLK (I)	CCLK (O)	CCLK (I)	CCLK (O)	CCLK (O)	CCLK (O)	CCLK (I)
		RDY/BUSY (O)	RDY/BUSY (O)	RCLK (O)	RCLK (O)	I/O
			RS (I)			I/O
			CS0 (I)			I/O
		DATA 7 (I)	DATA 7 (I)	DATA 7 (I)	DATA 7 (I)	I/O
		DATA 6 (I)	DATA 6 (I)	DATA 6 (I)	DATA 6 (I)	I/O
		DATA 5 (I)	DATA 5 (I)	DATA 5 (I)	DATA 5 (I)	I/O
		DATA 4 (I)	DATA 4 (I)	DATA 4 (I)	DATA 4 (I)	I/O
		DATA 3 (I)	DATA 3 (I)	DATA 3 (I)	DATA 3 (I)	I/O
		DATA 2 (I)	DATA 2 (I)	DATA 2 (I)	DATA 2 (I)	I/O
		DATA 1 (I)	DATA 1 (I)	DATA 1 (I)	DATA 1 (I)	I/O
DIN (I)	DIN (I)	DATA 0 (I)	DATA 0 (I)	DATA 0 (I)	DATA 0 (I)	I/O
DOUT	DOUT	DOUT	DOUT	DOUT	DOUT	SGCK4-GCK6-I/O
TDI	TDI	TDI	TDI	TDI	TDI	TDI-I/O
TCK	TCK	TCK	TCK	TCK	TCK	TCK-I/O
TMS	TMS	TMS	TMS	TMS	TMS	TMS-I/O
TDO	TDO	TDO	TDO	TDO	TDO	TDO-(O)
			WS (I)	A0	A0	I/O
				A1	A1	PGCK4-GCK7-I/O
			CS1	A2	A2	I/O
				A3	A3	I/O
				A4	A4	I/O
				A5	A5	I/O
				A6	A6	I/O
				A7	A7	I/O
				A8	A8	I/O
				A9	A9	I/O
				A10	A10	I/O
				A11	A11	I/O
				A12	A12	I/O
				A13	A13	I/O
				A14	A14	I/O
				A15	A15	SGCK1-GCK8-I/O
				A16	A16	PGCK1-GCK1-I/O
				A17	A17	I/O
				A18*	A18*	I/O
				A19*	A19*	I/O
				A20*	A20*	I/O
				A21*	A21*	I/O
						ALL OTHERS

Table 23: Pin Functions During Configuration

CONFIGURATION MODE <M2:M1:M0>						USER OPERATION
SLAVE SERIAL <1:1:1>	MASTER SERIAL <0:0:0>	SYNCH. PERIPHERAL <0:1:1>	ASYNCH. PERIPHERAL <1:0:1>	MASTER PARALLEL DOWN <1:1:0>	MASTER PARALLEL UP <1:0:0>	
M2(HIGH) (I)	M2(LOW) (I)	M2(LOW) (I)	M2(HIGH) (I)	M2(HIGH) (I)	M2(HIGH) (I)	(I)
M1(HIGH) (I)	M1(LOW) (I)	M1(HIGH) (I)	M1(LOW) (I)	M1(HIGH) (I)	M1(LOW) (I)	(O)
M0(HIGH) (I)	M0(LOW) (I)	M0(HIGH) (I)	M0(HIGH) (I)	M0(LOW) (I)	M0(LOW) (I)	(I)
HDC (HIGH)	HDC (HIGH)	HDC (HIGH)	HDC (HIGH)	HDC (HIGH)	HDC (HIGH)	I/O
LDC (LOW)	LDC (LOW)	LDC (LOW)	LDC (LOW)	LDC (LOW)	LDC (LOW)	I/O
INIT	INIT	INIT	INIT	INIT	INIT	I/O
DONE	DONE	DONE	DONE	DONE	DONE	DONE
PROGRAM (I)	PROGRAM (I)	PROGRAM (I)	PROGRAM (I)	PROGRAM (I)	PROGRAM (I)	PROGRAM
CCLK (I)	CCLK (O)	CCLK (I)	CCLK (O)	CCLK (O)	CCLK (O)	CCLK (I)
		RDY/BUSY (O)	RDY/BUSY (O)	RCLK (O)	RCLK (O)	I/O
			RS (I)			I/O
			CS0 (I)			I/O
		DATA 7 (I)	DATA 7 (I)	DATA 7 (I)	DATA 7 (I)	I/O
		DATA 6 (I)	DATA 6 (I)	DATA 6 (I)	DATA 6 (I)	I/O
		DATA 5 (I)	DATA 5 (I)	DATA 5 (I)	DATA 5 (I)	I/O
		DATA 4 (I)	DATA 4 (I)	DATA 4 (I)	DATA 4 (I)	I/O
		DATA 3 (I)	DATA 3 (I)	DATA 3 (I)	DATA 3 (I)	I/O
		DATA 2 (I)	DATA 2 (I)	DATA 2 (I)	DATA 2 (I)	I/O
		DATA 1 (I)	DATA 1 (I)	DATA 1 (I)	DATA 1 (I)	I/O
DIN (I)	DIN (I)	DATA 0 (I)	DATA 0 (I)	DATA 0 (I)	DATA 0 (I)	I/O
DOUT	DOUT	DOUT	DOUT	DOUT	DOUT	SGCK4-GCK6-I/O
TDI	TDI	TDI	TDI	TDI	TDI	TDI-I/O
TCK	TCK	TCK	TCK	TCK	TCK	TCK-I/O
TMS	TMS	TMS	TMS	TMS	TMS	TMS-I/O
TDO	TDO	TDO	TDO	TDO	TDO	TDO-(O)
			WS (I)	A0	A0	I/O
				A1	A1	PGCK4-GCK7-I/O
			CS1	A2	A2	I/O
				A3	A3	I/O
				A4	A4	I/O
				A5	A5	I/O
				A6	A6	I/O
				A7	A7	I/O
				A8	A8	I/O
				A9	A9	I/O
				A10	A10	I/O
				A11	A11	I/O
				A12	A12	I/O
				A13	A13	I/O
				A14	A14	I/O
				A15	A15	SGCK1-GCK8-I/O
				A16	A16	PGCK1-GCK1-I/O
				A17	A17	I/O
				A18*	A18*	I/O
				A19*	A19*	I/O
				A20*	A20*	I/O
				A21*	A21*	I/O
						ALL OTHERS

* XC4000X only

- Notes
1. A shaded table cell represents a 50 kΩ - 100 kΩ pull-up before and during configuration.
 2. (I) represents an input; (O) represents an output.
 3. INIT is an open-drain output during configuration.

Master Parallel Modes

In the two Master Parallel modes, the lead FPGA directly addresses an industry-standard byte-wide EPROM, and accepts eight data bits just before incrementing or decrementing the address outputs.

The eight data bits are serialized in the lead FPGA, which then presents the preamble data—and all data that overflows the lead device—on its DOUT pin. There is an internal delay of 1.5 CCLK periods, after the rising CCLK edge that accepts a byte of data (and also changes the EPROM address) until the falling CCLK edge that makes the LSB (D0) of this byte appear at DOUT. This means that DOUT changes on the falling CCLK edge, and the next FPGA in the daisy chain accepts data on the subsequent rising CCLK edge.

The PROM address pins can be incremented or decremented, depending on the mode pin settings. This option allows the FPGA to share the PROM with a wide variety of microprocessors and micro controllers. Some processors must boot from the bottom of memory (all zeros) while others must boot from the top. The FPGA is flexible and can load its configuration bitstream from either end of the memory.

Master Parallel Up mode is selected by a <100> on the mode pins (M2, M1, M0). The EPROM addresses start at 00000 and increment.

Master Parallel Down mode is selected by a <110> on the mode pins. The EPROM addresses start at 3FFFF and decrement.

Additional Address lines in XC4000 devices

The XC4000X devices have additional address lines (A18-A21) allowing the additional address space required to daisy-chain several large devices.

The extra address lines are programmable in XC4000EX devices. By default these address lines are not activated. In the default mode, the devices are compatible with existing XC4000 and XC4000E products. If desired, the extra address lines can be used by specifying the address lines option in bitgen as 22 (bitgen -g AddressLines:22). The lines (A18-A21) are driven when a master device detects, via the bitstream, that it should be using all 22 address lines. Because these pins will initially be pulled high by internal pull-ups, designers using Master Parallel Up mode should use external pull down resistors on pins A18-A21. If Master Parallel Down mode is used external resistors are not necessary.

All 22 address lines are always active in Master Parallel modes with XC4000XL devices. The additional address lines behave identically to the lower order address lines. If the Address Lines option in bitgen is set to 18, it will be ignored by the XC4000XL device.

The additional address lines (A18-A21) are not available in the PC84 package.

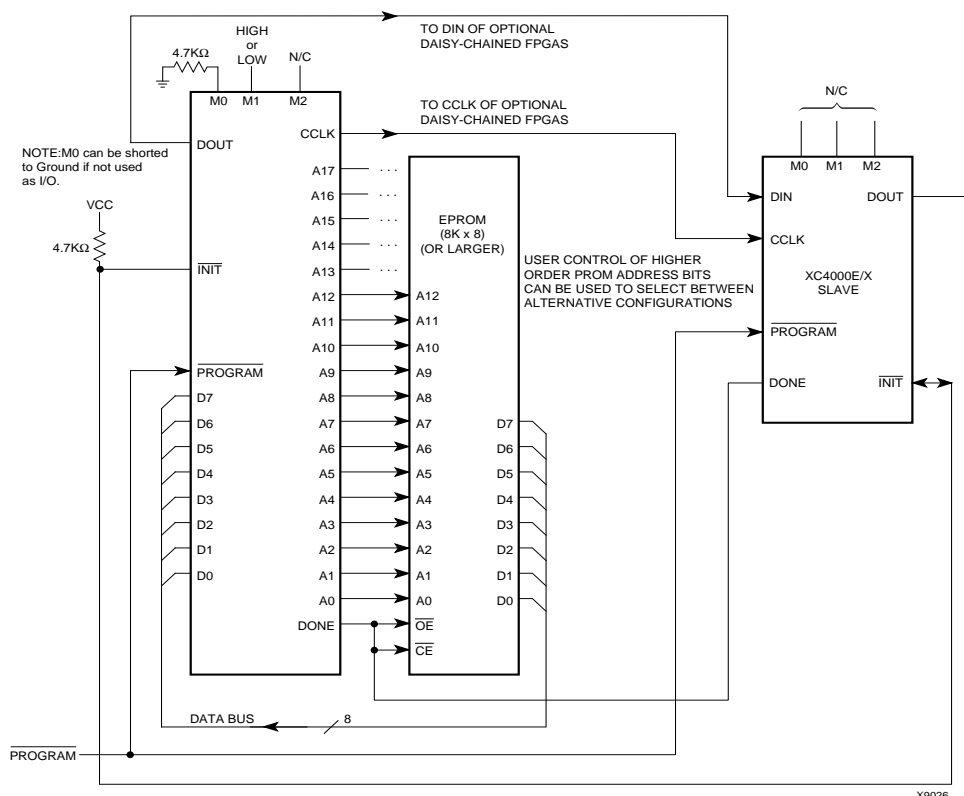
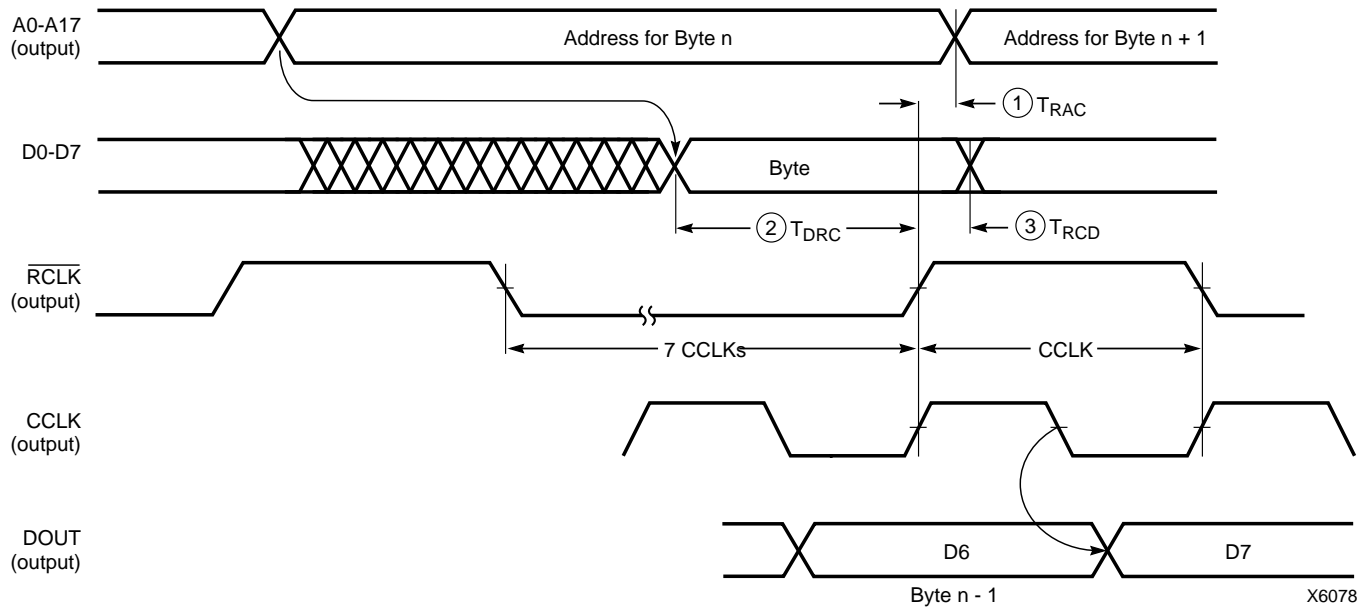


Figure 54: Master Parallel Mode Circuit Diagram



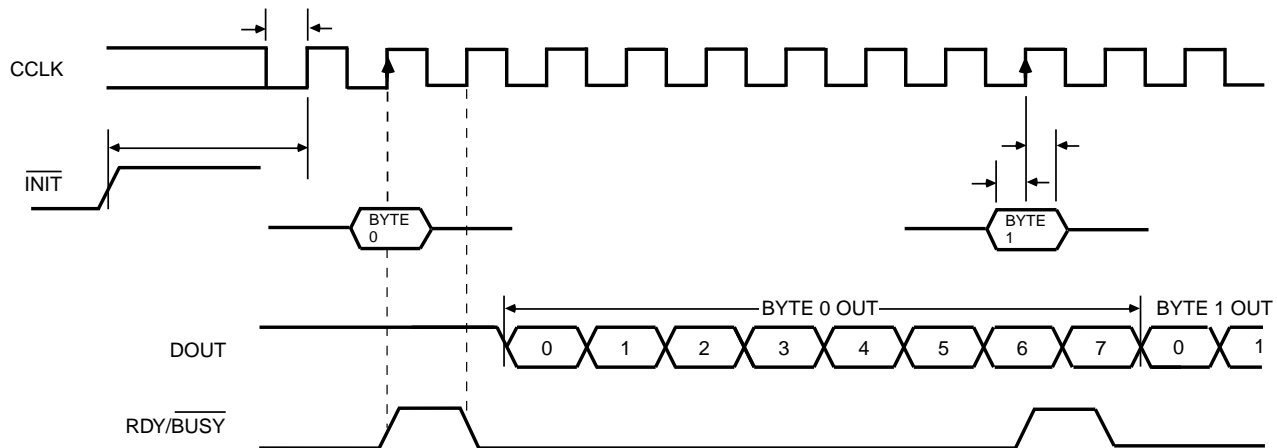
	Description	Symbol	Min	Max	Units
RCLK	Delay to Address valid	1 T_{RAC}	0	200	ns
	Data setup time	2 T_{DRC}	60		ns
	Data hold time	3 T_{RCD}	0		ns

Notes: 1. At power-up, V_{cc} must rise from 2.0 V to V_{cc} min in less than 25 ms, otherwise delay configuration by pulling PROGRAM Low until V_{cc} is valid.

2. The first Data byte is loaded and CCLK starts at the end of the first \overline{RCLK} active cycle (rising edge).

This timing diagram shows that the EPROM requirements are extremely relaxed. EPROM access time can be longer than 500 ns. EPROM data output has no hold-time requirements.

Figure 55: Master Parallel Mode Programming Switching Characteristics



X6096

	Description	Symbol	Min	Max	Units
CCLK	INIT (High) setup time	T_{IC}	5		μs
	D0 - D7 setup time	T_{DC}	60		ns
	D0 - D7 hold time	T_{CD}	0		ns
	CCLK High time	T_{CCH}	50		ns
	CCLK Low time	T_{CCL}	60		ns
	CCLK Frequency	F_{CC}		8	MHz

- Notes:
1. Peripheral Synchronous mode can be considered Slave Parallel mode. An external CCLK provides timing, clocking in the **first** data byte on the **second** rising edge of CCLK after INIT goes High. Subsequent data bytes are clocked in on every eighth consecutive rising edge of CCLK.
 2. The RDY/BUSY line goes High for one CCLK period after data has been clocked in, although synchronous operation does not require such a response.
 3. The pin name RDY/BUSY is a misnomer. In Synchronous Peripheral mode this is really an ACKNOWLEDGE signal.
 4. Note that data starts to shift out serially on the DOUT pin 0.5 CCLK periods after it was loaded in parallel. Therefore, additional CCLK pulses are clearly required after the last byte has been loaded.

Figure 57: Synchronous Peripheral Mode Programming Switching Characteristics

Asynchronous Peripheral Mode

Write to FPGA

Asynchronous Peripheral mode uses the trailing edge of the logic AND condition of \overline{WS} and $\overline{CS0}$ being Low and \overline{RS} and CS1 being High to accept byte-wide data from a micro-processor bus. In the lead FPGA, this data is loaded into a double-buffered UART-like parallel-to-serial converter and is serially shifted into the internal logic.

The lead FPGA presents the preamble data (and all data that overflows the lead device) on its DOUT pin. The RDY/ $\overline{\text{BUSY}}$ output from the lead FPGA acts as a handshake signal to the microprocessor. RDY/ $\overline{\text{BUSY}}$ goes Low when a byte has been received, and goes High again when the byte-wide input buffer has transferred its information into the shift register, and the buffer is ready to receive new data. A new write may be started immediately, as soon as the RDY/ $\overline{\text{BUSY}}$ output has gone Low, acknowledging receipt of the previous data. Write may not be terminated until RDY/ $\overline{\text{BUSY}}$ is High again for one CCLK period. Note that RDY/ $\overline{\text{BUSY}}$ is pulled High with a high-impedance pull-up prior to $\overline{\text{INIT}}$ going High.

The length of the $\overline{\text{BUSY}}$ signal depends on the activity in the UART. If the shift register was empty when the new byte was received, the $\overline{\text{BUSY}}$ signal lasts for only two CCLK periods. If the shift register was still full when the new byte was received, the $\overline{\text{BUSY}}$ signal can be as long as nine CCLK periods.

Note that after the last byte has been entered, only seven of its bits are shifted out. CCLK remains High with DOUT equal to bit 6 (the next-to-last bit) of the last byte entered.

The $\overline{\text{READY}}/\text{BUSY}$ handshake can be ignored if the delay from any one Write to the end of the next Write is guaranteed to be longer than 10 CCLK periods.

Status Read

The logic AND condition of the $\overline{CS0}$, CS1 and \overline{RS} inputs puts the device status on the Data bus.

- D7 High indicates Ready
- D7 Low indicates Busy
- D0 through D6 go unconditionally High

It is mandatory that the whole start-up sequence be started and completed by one byte-wide input. Otherwise, the pins used as Write Strobe or Chip Enable might become active outputs and interfere with the final byte transfer. If this transfer does not occur, the start-up sequence is not completed all the way to the finish (point F in [Figure 47 on page 53](#)).

In this case, at worst, the internal reset is not released. At best, Readback and Boundary Scan are inhibited. The length-count value, as generated by the XACTstep software, ensures that these problems never occur.

Although RDY/ $\overline{\text{BUSY}}$ is brought out as a separate signal, microprocessors can more easily read this information on one of the data lines. For this purpose, D7 represents the RDY/ $\overline{\text{BUSY}}$ status when $\overline{\text{RS}}$ is Low, $\overline{\text{WS}}$ is High, and the two chip select lines are both active.

Asynchronous Peripheral mode is selected by a <101> on the mode pins (M2, M1, M0).

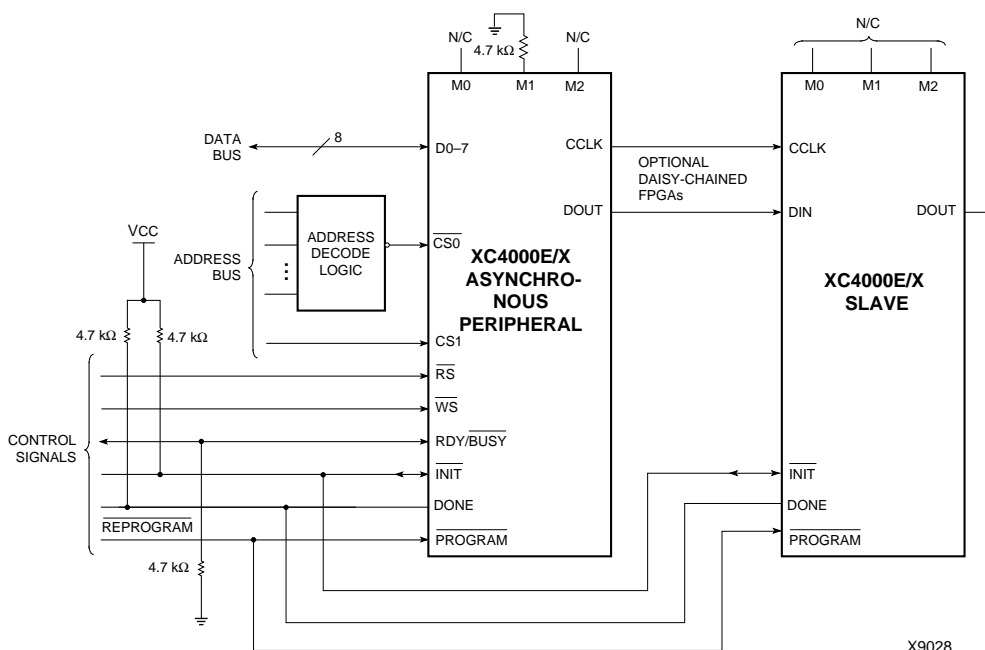
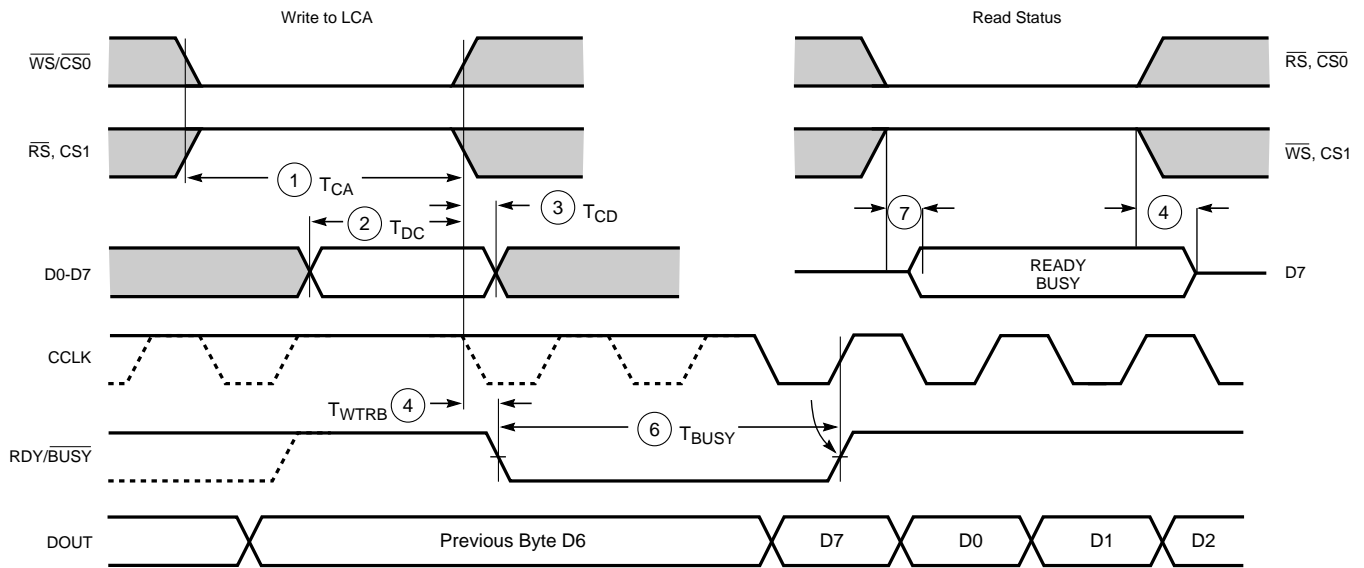


Figure 58: Asynchronous Peripheral Mode Circuit Diagram



X6097

	Description	Symbol	Min	Max	Units
Write	Effective Write time (CS0, WS=Low; RS, CS1=High)	1 T_{CA}	100		ns
	DIN setup time	2 T_{DC}	60		ns
	DIN hold time	3 T_{CD}	0		ns
RDY	RDY/BUSY delay after end of Write or Read	4 T_{WTRB}		60	ns
	RDY/BUSY active after beginning of Read	7		60	ns
	RDY/BUSY Low output (Note 4)	6 T_{BUSY}	2	9	CCLK periods

- Notes:
1. Configuration must be delayed until the \overline{INIT} pins of all daisy-chained FPGAs are High.
 2. The time from the end of \overline{WS} to CCLK cycle for the new byte of data depends on the completion of previous byte processing and the phase of the internal timing generator for CCLK.
 3. CCLK and DOUT timing is tested in slave mode.
 4. T_{BUSY} indicates that the double-buffered parallel-to-serial converter is not yet ready to receive new data. The shortest T_{BUSY} occurs when a byte is loaded into an empty parallel-to-serial converter. The longest T_{BUSY} occurs when a new word is loaded into the input register before the second-level buffer has started shifting out data.

This timing diagram shows very relaxed requirements. Data need not be held beyond the rising edge of \overline{WS} . RDY/BUSY will go active within 60 ns after the end of \overline{WS} . A new write may be asserted immediately after RDY/BUSY goes Low, but write may not be terminated until RDY/BUSY has been High for one CCLK period.

Figure 59: Asynchronous Peripheral Mode Programming Switching Characteristics